





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
20V	$42m\Omega @ V_{GS} = 10V$	3.5A
20 v	$45m\Omega$ @ $V_{GS} = 4.5V$	3.3A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Motor Control
- Power Management Functions
- Backlighting

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

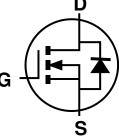
Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.006 grams (Approximate)

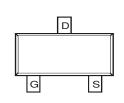




Top View



Equivalent Circuit



Top View

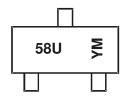
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2058UW-7	SOT323	3000/Tape & Reel
DMN2058UW-13	SOT323	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and -1000ppm antimony compounds.
 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



58U= Product Type Marking Code YM or $\overline{Y}M$ = Date Code Marking for SAT Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

 ale Code Rey				-					
Year	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	E	F	G	Н	I	J	K	L	М

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	20	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 10V	I _D	3.5 3.0	А	
Maximum Continuous Body Diode Forward Current	(Note 6)	I _S	1.0	Α
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%	6) (Note 6)	I _{DM}	20	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	0.5	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	259	°C/W
Total Power Dissipation (Note 6)		P_{D}	0.7	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	175	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

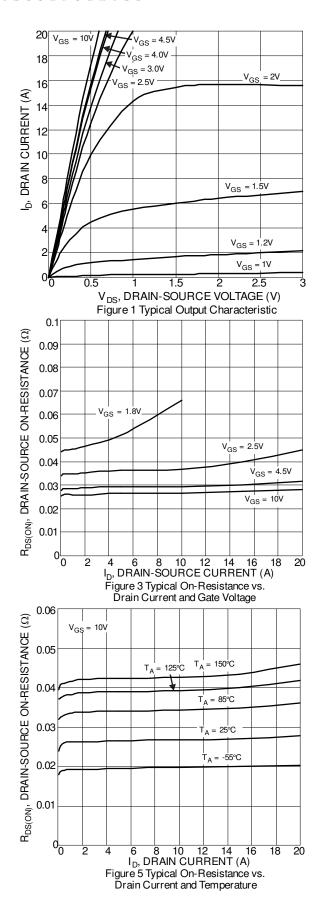
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

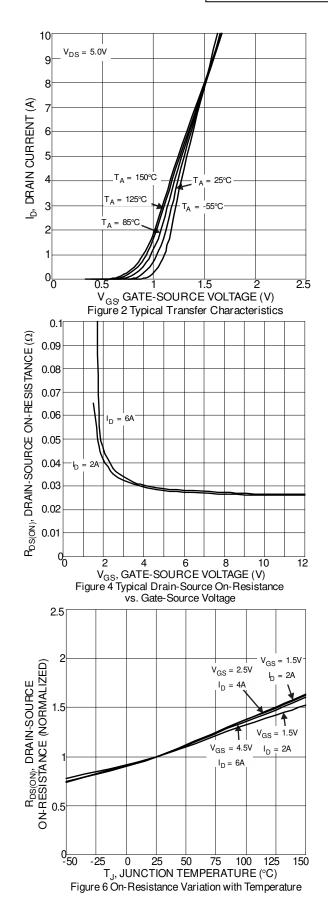
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.4	_	1.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
			31.5	42		$V_{GS} = 10V, I_D = 3A$
Static Drain-Source On-Resistance			32	45	0	$V_{GS} = 4.5V, I_D = 2A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	40.5	60	mΩ	V _{GS} = 2.5V, I _D = 2A
			48	91		V _{GS} = 1.8V, I _D = 1A
Diode Forward Voltage	V _{SD}	_	0.78	1.2	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 8)	•	l.				
Input Capacitance	C _{iss}	_	281	_	pF	V 40V V 0V
Output Capacitance	Coss	_	50	_	pF	$V_{DS} = 10V, V_{GS} = 0V$ - f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	39	_	pF	71 = 1.0WHZ
Gate Resistance	Rg	_	3.1	_	Ω	f = 1.0MHz , V _{GS} = 0V, V _{DS} = 0V
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	3.6	_	nC	
Total Gate Charge (V _{GS} = 10V)	Qq	_	7.7	_	nC	7, 40,4 0.04
Gate-Source Charge	Q _{qs}	_	0.5	_	nC	$V_{DS} = 10V, I_D = 6.0A$
Gate-Drain Charge	Q _{gd}	_	0.9	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	2.0	_	ns	
Turn-On Rise Time	t _R	_	4.9	_	ns	$V_{GS} = 4.5V, V_{DD} = 10V, R_g = 6\Omega,$
Turn-Off Delay Time	t _{D(OFF)}	_	9.9	_	ns	$I_D = 6.0A$
Turn-Off Fall Time	t _F	_	3.3	_	ns	
Body Diode Reverse Recovery Time	t _{RR}	_	5.4	_	ns	I _F = 6.0A, di/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	_	0.7	_	nC	I _F = 6.0A, di/dt = 100A/µs

Notes:

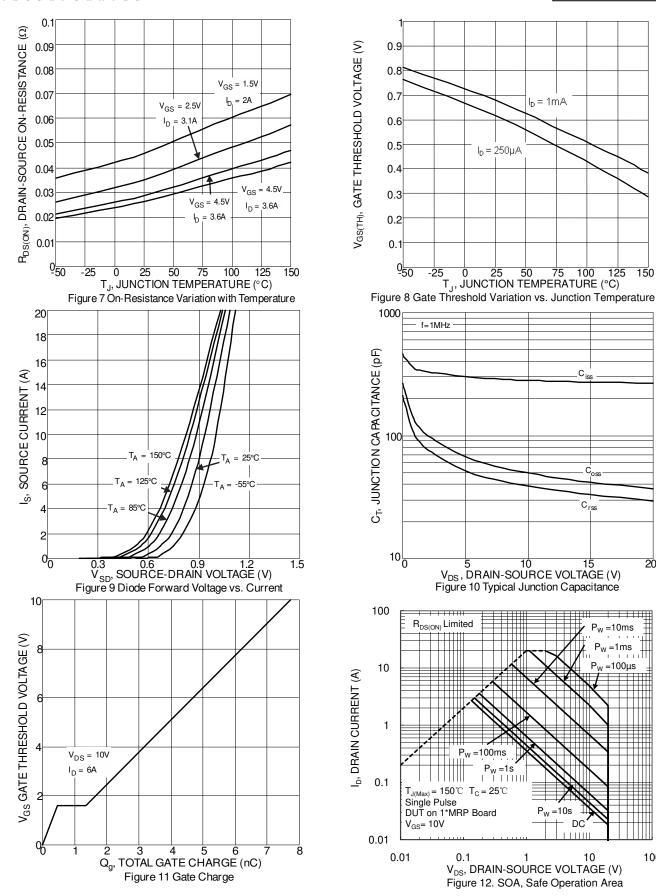
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.











100

20



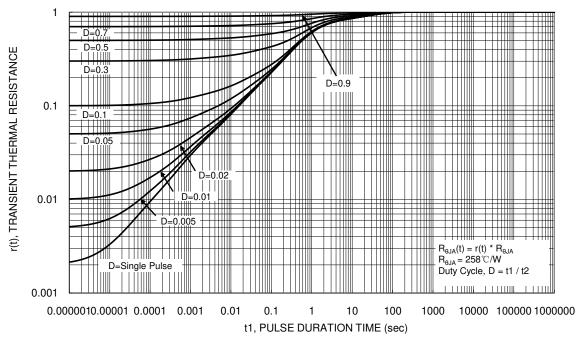


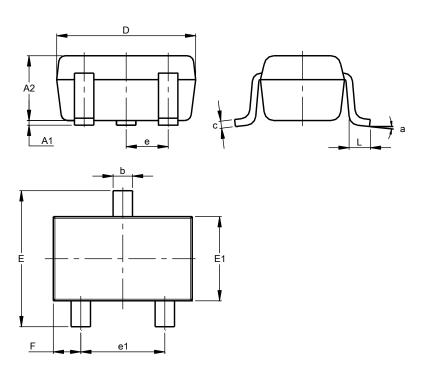
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323

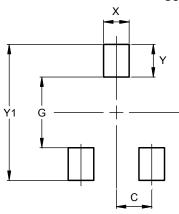


	SOT323							
Dim								
A 1	0.00	0.10	0.05					
A2	0.90	1.00	0.95					
b	0.25	0.40	0.30					
С	0.10	0.18	0.11					
D	1.80	2.20	2.15					
Е	2.00	2.20	2.10					
E1	1.15	1.35	1.30					
е	C).650 B	SC					
e1	1.20	1.40	1.30					
F	0.375	0.475	0.425					
L	0.25	0.40	0.30					
а	0°	8°						
All	All Dimensions in mm							

Suggested Pad Layout

 $\label{please} Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

SOT323



Dimensions	Value (in mm)
С	0.650
G	1.300
X	0.470
Υ	0.600
Y1	2.500



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